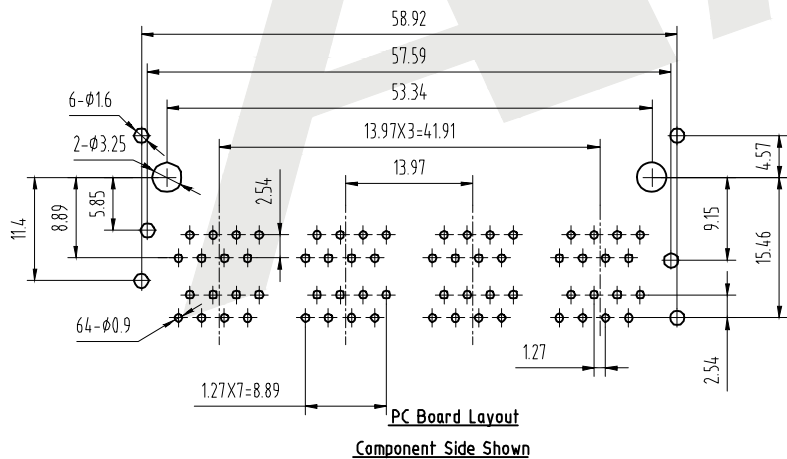
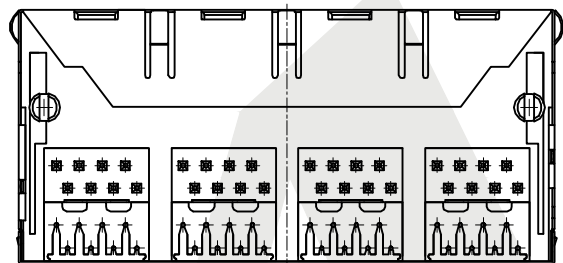
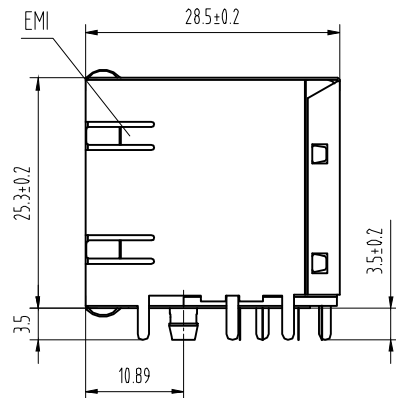
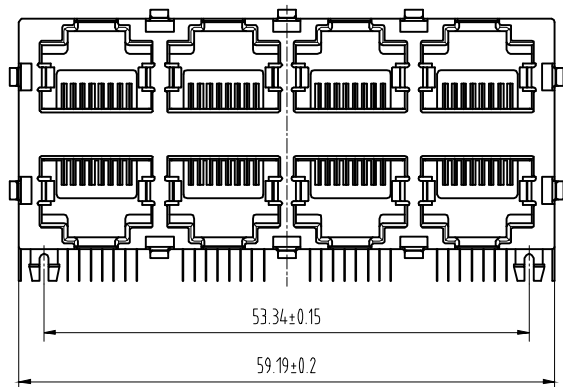


HSF



NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING  $1\mu\sim 50\mu$  "OVER NICKEL IN CONTACT AREA.  $150\mu$  " TIN PLATIN. OVER NICKEL IN SOLDER AREA

4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATEI ELECTRICAL

1. VOLTAGE RATING: 125V AC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30 MILLIOHMS MAX
4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVIORNMENTAL

1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$

Order code:

ATRJ5921 - 8P - 8C - X - C1 - J

①      ②      ③      ④      ⑤      ⑥

① SERIES NO:

② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)

③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)

④ Contact Plating

- G0: Gold flash
- G1: 3U" Gold
- G2: 5U" Gold
- G3: 10U" Gold
- G4: 15U" Gold
- G5: 30U" Gold
- SN: Tin

⑤ Shield

- A: W/O Shield
- B: Half Shield
- C: Shield W/Eml
- D: Shield W/O Eml

⑥ Ports

- A: 1X1P    G: 2\*1P
- B: 1X2P    H: 2\*2P
- C: 1X4P    I: 2\*3P
- D: 1X5P    J: 2\*4P
- E: 1X6P    K: 2\*6P
- F: 1X8P    L: 2\*8P

Unless Otherwise specified tolerance  
X. ±0.35    X.XX: ±0.20  
X.X: ±0.25    X.XXX: ±0.15

**Antenk**® ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

SCALE: As Shown    UNIT: mm  
DRAW Wu Feng Rong    DATE 22/03/2018  
CHECK BobYang    DATE 22/03/2018

TITLE: RJ45 Jack side entry full shielded 2X4P with EMI

DRAWING NO: ATRJ5921-8P8C-X-C1-J

PRODUCT NO: ATRJ5921-8P8C-X-C1-J



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		